PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data			
1.1 Company STMicroelectronics International N.V		STMicroelectronics International N.V	
1.2 PCN No.		MDG/17/9977	
1.3 Title of PCN		Transfer assembly plant from Stats ChipPAC Shanghai China (SCC) to Stats ChipPAC Jiangyi China (JSCC) for products in UFQFPN 5x5 & 7x7 packages	
1.4 Product Category		UFQFPN 5x5 and 7x7 packaged products	
1.5 Issue date		2017-02-17	

2. PCN Team		
2.1 Contact supplier		
2.1.1 Name	MARSHALL DAVE	
2.1.2 Phone		
2.1.3 Email	dave.marshall@st.com	
2.2 Change responsibility		
2.2.1 Product Manager	Michel BUFFA	
2.1.2 Marketing Manager	Daniel COLONNA	
2.1.3 Quality Manager	Pascal NARCHE	

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials		Stats ChipPAC Shanghai China (SCC), Stats ChipPAC Jiangyin China (JSCC)

4. Description of change		
	Old	New
4.1 Description	Current location : Stats ChipPAC Shanghai China (SCC)	Transfer from Stats ChipPAC Shanghai China (SCC) to Stats ChipPAC Jiangyin China (JSCC) location. See more information on PCN 9977 – Additional information document attached.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Change lead shape : with neck design. See in PCN 9977 – Additional information document attached. No change in fit, function, reliability or process ability.	

5. Reason / motivation for change		
5.1 Motivation Due to Shanghai China site closure, production is relocated to Jiangyin China site. This Product Change Notification (PCN) concerns only UFQFPN 5x5 and 7x7 package products.		
5.2 Customer Benefit	SERVICE CONTINUITY	

6. Marking of parts / traceability of change	
6.1 Description	Traceability is described in PCN9977_Additional information attached document

7. Timing / schedule	
7.1 Date of qualification results	2017-05-26
7.2 Intended start of delivery	2017-06-26
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	Description 9977 PCN9977_RERMCD1622- UQFN5x5_7x7 JSCC- MCD QA reliability plan.pdf		
8.2 Qualification report and qualification results		Issue Date	2017-02-17

9. Attachments (additional documentations)

9977 Public product.pdf 9977 PCN9977_Additional information.pdf 9977 PCN9977_RERMCD1622- UQFN5x5_7x7 JSCC- MCD QA reliability plan.pdf

10. Affected parts			
10. 1 Current		10.2 New (if applicable)	
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No	
2456959	STM32F091CBU6		
2456960	STM32F091CCU6		
2456961	STM32F091CCU7		
2503245	STM32F098CCU6		
2456965	STM32F411CEU6		
2503258	STM32F411CEU7		
2503323	STM8L151C6U6TR		
2518134	STM32F410CBU6		
2503251	STM32F301K8U7		
2503294	STM32L052K8U3TR		
2518133	STM32F318K8U7		
2488322	STM32L051K8U3		
2488323	STM32L051K8U6		
2488324	STM32L051K8U7		
2488346	STM32L062K8U6		
2518144	STM32L071KZU6		

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